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For Immediate Release

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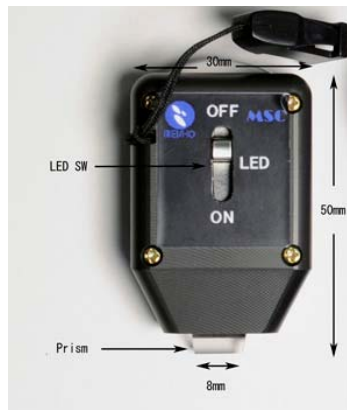
Seika Machinery Introduces PR1 Pocket Handy BGA Solder Ball Checker

TORRANCE, CA — May 2010 — Seika Machinery, Inc., a leading provider of advanced machinery, materials and engineering services, introduces M.S. Engineering Co. Ltd.'s PR1 BGA Solder Ball Checker for fast and accurate inspection of BGA soldering and QFP lead sections.

The easy-to-use system is the ideal solution for checking BGA solder balls. The handheld system provides fast and accurate inspection of the soldered points and surface of BGAs, and features a conductive body for ESD. It also enables visual inspection of QFP leads as well as chip parts. As an additional benefit, the small checker (50 x 30 x 15 mm, weighing 25 g) fits in a handy pocket and comes standard with a wrist strap for convenience.

The PR1 is capable of inspecting the interior section of BGA packages using a battery-powered white-LED lighting system. With an expanded lens, the PR1 is capable of up to 7X magnification.

For more information about the PR1 BGA Solder Ball Checker, contact Seika Machinery at 310-540-7310 or e-mail info@seikausa.com.



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About Seika Machinery, Inc.

Seika Machinery, Inc. (SMI) is a subsidiary of Seika Corporation, Japan and member of the Mitsubishi Global Group. SMI provides electronics manufacturers with advanced machinery, superior materials and engineering services.